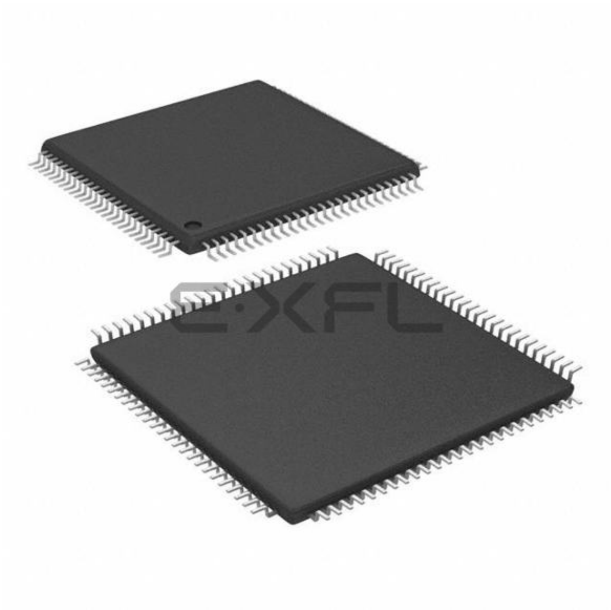

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### What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "Embedded - Microcontrollers"

| **Details** | |
|---|---|
| Product Status | Active |
| Core Processor | PIC |
| Core Size | 16-Bit |
| Speed | 40 MIPs |
| Connectivity | I²C, IrDA, LINbus, SPI, UART/USART |
| Peripherals | Brown-out Detect/Reset, DMA, POR, PWM, WDT |
| Number of I/O | 85 |
| Program Memory Size | 256KB (85.5K x 24) |
| Program Memory Type | FLASH |
| EEPROM Size | - |
| RAM Size | 16K x 8 |
| Voltage - Supply (Vcc/Vdd) | 3V ~ 3.6V |
| Data Converters | A/D 32x10b, 32x12b |
| Oscillator Type | Internal |
| Operating Temperature | -40°C ~ 85°C (TA) |
| Mounting Type | Surface Mount |
| Package / Case | 100-TQFP |
| Supplier Device Package | 100-TQFP (14x14) |
| Purchase URL | https://www.e-xfl.com/product-detail/microchip-technology/pic24hj256gp210-i-pf |

## 2.0 GUIDELINES FOR GETTING STARTED WITH 16-BIT MICROCONTROLLERS

| | |
|---|---|
| **Note:** | This data sheet summarizes the features of the PIC24HJXXXGPX06/X08/X10 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"PIC24H Family Reference Manual"*, which is available from the Microchip website (www.microchip.com). |

### 2.1 Basic Connection Requirements

Getting started with the PIC24HJXXXGPX06/X08/X10 family of 16-bit Microcontrollers (MCUs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins (see **Section 2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins (regardless if ADC module is not used) (see **Section 2.2 "Decoupling Capacitors"**)
- VCAP/VDDCORE (see **Section 2.3 "Capacitor on Internal Voltage Regulator (VCAP/VDDCORE)"**)
- $\overline{\text{MCLR}}$ pin (see **Section 2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see **Section 2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins when external oscillator source is used (see **Section 2.6 "External Oscillator Pins"**)

Additionally, the following pins may be required:

- VREF+/VREF- pins used when external voltage reference for ADC module is implemented

| | |
|---|---|
| **Note:** | The AVDD and AVSS pins must be connected independent of the ADC voltage reference source. |

### 2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** Recommendation of 0.1 µF (100 nF), 10-20V. This capacitor should be a low-ESR and have resonance frequency in the range of 20 MHz and higher. It is recommended that ceramic capacitors be used.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high frequency noise:** If the board is experiencing high frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum thereby reducing PCB track inductance.

## 2.5 ICSP Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes, and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high ($V_{IH}$) and input low ($V_{IL}$) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® ICD 2, MPLAB ICD 3, or MPLAB REAL ICE™.

For more information on ICD 2, ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip website.

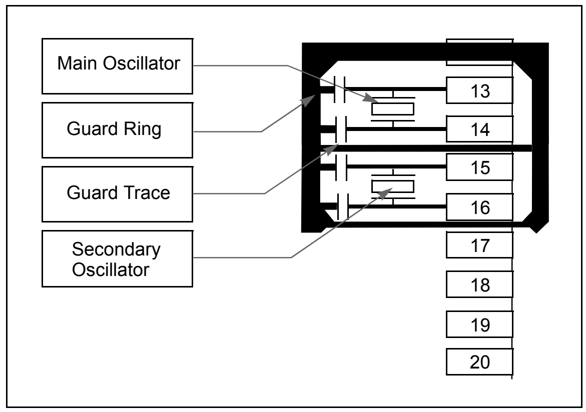
- *"MPLAB® ICD 2 In-Circuit Debugger User's Guide"* DS51331
- *"Using MPLAB® ICD 2"* (poster) DS51265
- *"MPLAB® ICD 2 Design Advisory"* DS51566
- *"Using MPLAB® ICD 3 In-Circuit Debugger"* (poster) DS51765
- *"MPLAB® ICD 3 Design Advisory"* DS51764
- *"MPLAB® REAL ICE™ In-Circuit Emulator User's Guide"* DS51616
- *"Using MPLAB® REAL ICE™"* (poster) DS51749

## 2.6 External Oscillator Pins

Many MCUs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 9.0 "Oscillator Configuration"** for details).

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is shown in Figure 2-3.

**FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT**



**REGISTER 3-2: CORCON: CORE CONTROL REGISTER**

| U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
|---|---|---|---|---|---|---|---|
| — | — | — | — | — | — | — | — |
| bit 15 | | | | | | | bit 8 |

| U-0 | U-0 | U-0 | U-0 | R/C-0 | R/W-0 | U-0 | U-0 |
|---|---|---|---|---|---|---|---|
| — | — | — | — | IPL3(1) | PSV | — | — |
| bit 7 | | | | | | | bit 0 |

| **Legend:** | C = Clear only bit | | |
|---|---|---|---|
| R = Readable bit | W = Writable bit | -n = Value at POR | ‘1’ = Bit is set |
| 0’ = Bit is cleared | ‘x = Bit is unknown | U = Unimplemented bit, read as ‘0’ | |

bit 15-4 **Unimplemented:** Read as ‘0’

bit 3 **IPL3:** CPU Interrupt Priority Level Status bit 3(1)
1 = CPU interrupt priority level is greater than 7
0 = CPU interrupt priority level is 7 or less

bit 2 **PSV:** Program Space Visibility in Data Space Enable bit
1 = Program space visible in data space
0 = Program space not visible in data space

bit 1-0 **Unimplemented:** Read as ‘0’

**Note 1:** The IPL3 bit is concatenated with the IPL<2:0> bits (SR<7:5>) to form the CPU interrupt priority level.

**TABLE 4-20: ECAN1 REGISTER MAP WHEN C1CTRL1.WIN = 1 FOR PIC24HJXXXGP506/510/610 DEVICES ONLY (CONTINUED)**

| File Name | Addr | Bit 15 | Bit 14 | Bit 13 | Bit 12 | Bit 11 | Bit 10 | Bit 9 | Bit 8 | Bit 7 | Bit 6 | Bit 5 | Bit 4 | Bit 3 | Bit 2 | Bit 1 | Bit 0 | All Resets |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| C1RXF11EID | 046E | EID<15:8> | | | | | | | | EID<7:0> | | | | | | | | xxxx |
| C1RXF12SID | 0470 | SID<10:3> | | | | | | | | SID<2:0> | | | — | EXIDE | — | EID<17:16> | | xxxx |
| C1RXF12EID | 0472 | EID<15:8> | | | | | | | | EID<7:0> | | | | | | | | xxxx |
| C1RXF13SID | 0474 | SID<10:3> | | | | | | | | SID<2:0> | | | — | EXIDE | — | EID<17:16> | | xxxx |
| C1RXF13EID | 0476 | EID<15:8> | | | | | | | | EID<7:0> | | | | | | | | xxxx |
| C1RXF14SID | 0478 | SID<10:3> | | | | | | | | SID<2:0> | | | — | EXIDE | — | EID<17:16> | | xxxx |
| C1RXF14EID | 047A | EID<15:8> | | | | | | | | EID<7:0> | | | | | | | | xxxx |
| C1RXF15SID | 047C | SID<10:3> | | | | | | | | SID<2:0> | | | — | EXIDE | — | EID<17:16> | | xxxx |
| C1RXF15EID | 047E | EID<15:8> | | | | | | | | EID<7:0> | | | | | | | | xxxx |

**Legend:** x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal for PinHigh devices.

**REGISTER 6-1: RCON: RESET CONTROL REGISTER(1)**

| R/W-0 | R/W-0 | U-0 | U-0 | U-0 | U-0 | U-0 | R/W-0 |
|---|---|---|---|---|---|---|---|
| TRAPR | IOPUWR | — | — | — | — | — | VREGS |
| bit 15 | | | | | | | bit 8 |

| R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-1 | R/W-1 |
|---|---|---|---|---|---|---|---|
| EXTR | SWR | SWDTEN(2) | WDTO | SLEEP | IDLE | BOR | POR |
| bit 7 | | | | | | | bit 0 |

| **Legend:** | | | |
|---|---|---|---|
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read as '0' | |
| -n = Value at POR | '1' = Bit is set | '0' = Bit is cleared | x = Bit is unknown |

bit 15 **TRAPR:** Trap Reset Flag bit
1 = A Trap Conflict Reset has occurred
0 = A Trap Conflict Reset has not occurred

bit 14 **IOPUWR:** Illegal Opcode or Uninitialized W Access Reset Flag bit
1 = An illegal opcode detection, an illegal address mode or uninitialized W register used as an Address Pointer caused a Reset
0 = An illegal opcode or uninitialized W Reset has not occurred

bit 13-9 **Unimplemented:** Read as '0'

bit 8 **VREGS:** Voltage Regulator Standby During Sleep bit
1 = Voltage regulator is active during Sleep
0 = Voltage regulator goes into Standby mode during Sleep

bit 7 **EXTR:** External Reset ($\overline{\text{MCLR}}$) Pin bit
1 = A Master Clear (pin) Reset has occurred
0 = A Master Clear (pin) Reset has not occurred

bit 6 **SWR:** Software Reset (Instruction) Flag bit
1 = A `RESET` instruction has been executed
0 = A `RESET` instruction has not been executed

bit 5 **SWDTEN:** Software Enable/Disable of WDT bit(2)
1 = WDT is enabled
0 = WDT is disabled

bit 4 **WDTO:** Watchdog Timer Time-out Flag bit
1 = WDT time-out has occurred
0 = WDT time-out has not occurred

bit 3 **SLEEP:** Wake-up from Sleep Flag bit
1 = Device has been in Sleep mode
0 = Device has not been in Sleep mode

bit 2 **IDLE:** Wake-up from Idle Flag bit
1 = Device was in Idle mode
0 = Device was not in Idle mode

bit 1 **BOR:** Brown-out Reset Flag bit
1 = A Brown-out Reset has occurred
0 = A Brown-out Reset has not occurred

bit 0 **POR:** Power-on Reset Flag bit
1 = A Power-on Reset has occurred
0 = A Power-on Reset has not occurred

**Note 1:** All of the Reset status bits may be set or cleared in software. Setting one of these bits in software does not cause a device Reset.

**2:** If the FWDTEN Configuration bit is '1' (unprogrammed), the WDT is always enabled, regardless of the SWDTEN bit setting.

**REGISTER 7-10: IEC0: INTERRUPT ENABLE CONTROL REGISTER 0**

| U-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
|---|---|---|---|---|---|---|---|
| — | DMA1IE | AD1IE | U1TXIE | U1RXIE | SPI1IE | SPI1EIE | T3IE |
| bit 15 | | | | | | | bit 8 |

| R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
|---|---|---|---|---|---|---|---|
| T2IE | OC2IE | IC2IE | DMA0IE | T1IE | OC1IE | IC1IE | INT0IE |
| bit 7 | | | | | | | bit 0 |

| **Legend:** | | | |
|---|---|---|---|
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read as ‘0’ | |
| -n = Value at POR | ‘1’ = Bit is set | ‘0’ = Bit is cleared | x = Bit is unknown |

bit 15 **Unimplemented:** Read as ‘0’

bit 14 **DMA1IE:** DMA Channel 1 Data Transfer Complete Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 13 **AD1IE:** ADC1 Conversion Complete Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 12 **U1TXIE:** UART1 Transmitter Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 11 **U1RXIE:** UART1 Receiver Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 10 **SPI1IE:** SPI1 Event Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 9 **SPI1EIE:** SPI1 Error Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 8 **T3IE:** Timer3 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 7 **T2IE:** Timer2 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 6 **OC2IE:** Output Compare Channel 2 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 5 **IC2IE:** Input Capture Channel 2 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 4 **DMA0IE:** DMA Channel 0 Data Transfer Complete Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 3 **T1IE:** Timer1 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

NOTES:

**REGISTER 15-1: OCxCON: OUTPUT COMPARE x CONTROL REGISTER (x = 1, 2)**

| U-0 | U-0 | R/W-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
|---|---|---|---|---|---|---|---|
| — | — | OCSIDL | — | — | — | — | — |
| bit 15 | | | | | | | bit 8 |

| U-0 | U-0 | U-0 | R-0, HC | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
|---|---|---|---|---|---|---|---|
| — | — | — | OCFLT | OCTSEL | OCM<2:0> | | |
| bit 7 | | | | | | | bit 0 |

| **Legend:** | HC = Hardware Clearable bit | | |
|---|---|---|---|
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read as '0' | |
| -n = Value at POR | '1' = Bit is set | '0' = Bit is cleared | x = Bit is unknown |

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **OCSIDL:** Stop Output Compare in Idle Mode Control bit
1 = Output Compare x halts in CPU Idle mode
0 = Output Compare x continues to operate in CPU Idle mode

bit 12-5 **Unimplemented:** Read as '0'

bit 4 **OCFLT:** PWM Fault Condition Status bit
1 = PWM Fault condition has occurred (cleared in hardware only)
0 = No PWM Fault condition has occurred (this bit is only used when OCM<2:0> = 111)

bit 3 **OCTSEL:** Output Compare Timer Select bit
1 = Timer3 is the clock source for Compare x
0 = Timer2 is the clock source for Compare x

bit 2-0 **OCM<2:0>:** Output Compare Mode Select bits
111 = PWM mode on OCx, Fault pin enabled
110 = PWM mode on OCx, Fault pin disabled
101 = Initialize OCx pin low, generate continuous output pulses on OCx pin
100 = Initialize OCx pin low, generate single output pulse on OCx pin
011 = Compare event toggles OCx pin
010 = Initialize OCx pin high, compare event forces OCx pin low
001 = Initialize OCx pin low, compare event forces OCx pin high
000 = Output compare channel is disabled

**REGISTER 18-2: UxSTA: UARTx STATUS AND CONTROL REGISTER (CONTINUED)**

bit 5 **ADDEN:** Address Character Detect bit (bit 8 of received data = 1)
- 1 = Address Detect mode enabled. If 9-bit mode is not selected, this does not take effect
- 0 = Address Detect mode disabled

bit 4 **RIDLE:** Receiver Idle bit (read-only)
- 1 = Receiver is Idle
- 0 = Receiver is active

bit 3 **PERR:** Parity Error Status bit (read-only)
- 1 = Parity error has been detected for the current character (character at the top of the receive FIFO)
- 0 = Parity error has not been detected

bit 2 **FERR:** Framing Error Status bit (read-only)
- 1 = Framing error has been detected for the current character (character at the top of the receive FIFO)
- 0 = Framing error has not been detected

bit 1 **OERR:** Receive Buffer Overrun Error Status bit (read/clear only)
- 1 = Receive buffer has overflowed
- 0 = Receive buffer has not overflowed. Clearing a previously set OERR bit (1 → 0 transition) will reset the receiver buffer and the UxRSR to the empty state

bit 0 **URXDA:** Receive Buffer Data Available bit (read-only)
- 1 = Receive buffer has data, at least one more character can be read
- 0 = Receive buffer is empty

**Note 1:** Refer to **Section 17. "UART"** (DS70232) in the *"PIC24H Family Reference Manual"* for information on enabling the UART module for transmit operation.

# 19.0 ENHANCED CAN (ECAN™) MODULE

| Note: | This data sheet summarizes the features of the PIC24HJXXXGPX06/X08/X10 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"PIC24H Family Reference Manual"*, **Section 21. "Enhanced Controller Area Network (ECAN™)"** (DS70226), which is available from the Microchip website (www.microchip.com). |
|---|---|

## 19.1 Overview

The Enhanced Controller Area Network (ECAN™) module is a serial interface, useful for communicating with other CAN modules or microcontroller devices. This interface/protocol was designed to allow communications within noisy environments. The PIC24HJXXXGPX06/X08/X10 devices contain up to two ECAN modules.

The CAN module is a communication controller implementing the CAN 2.0 A/B protocol, as defined in the BOSCH specification. The module will support CAN 1.2, CAN 2.0A, CAN 2.0B Passive and CAN 2.0B Active versions of the protocol. The module implementation is a full CAN system. The CAN specification is not covered within this data sheet. The reader may refer to the BOSCH CAN specification for further details.

The module features are as follows:

- Implementation of the CAN protocol, CAN 1.2, CAN 2.0A and CAN 2.0B
- Standard and extended data frames
- 0-8 bytes data length
- Programmable bit rate up to 1 Mbit/sec
- Automatic response to remote transmission requests
- Up to 8 transmit buffers with application specified prioritization and abort capability (each buffer may contain up to 8 bytes of data)
- Up to 32 receive buffers (each buffer may contain up to 8 bytes of data)
- Up to 16 full (standard/extended identifier) acceptance filters
- 3 full acceptance filter masks
- DeviceNet™ addressing support
- Programmable wake-up functionality with integrated low-pass filter
- Programmable Loopback mode supports self-test operation
- Signaling via interrupt capabilities for all CAN receiver and transmitter error states
- Programmable clock source
- Programmable link to input capture module (IC2 for both CAN1 and CAN2) for time-stamping and network synchronization
- Low-power Sleep and Idle mode

The CAN bus module consists of a protocol engine and message buffering/control. The CAN protocol engine handles all functions for receiving and transmitting messages on the CAN bus. Messages are transmitted by first loading the appropriate data registers. Status and errors can be checked by reading the appropriate registers. Any message detected on the CAN bus is checked for errors and then matched against filters to see if it should be received and stored in one of the receive registers.

## 19.2 Frame Types

The CAN module transmits various types of frames which include data messages, remote transmission requests and as other frames that are automatically generated for control purposes. The following frame types are supported:

- Standard Data Frame:

  A standard data frame is generated by a node when the node wishes to transmit data. It includes an 11-bit standard identifier (SID) but not an 18-bit extended identifier (EID).

- Extended Data Frame:

  An extended data frame is similar to a standard data frame but includes an extended identifier as well.

- Remote Frame:

  It is possible for a destination node to request the data from the source. For this purpose, the destination node sends a remote frame with an identifier that matches the identifier of the required data frame. The appropriate data source node will then send a data frame as a response to this remote request.

- Error Frame:

  An error frame is generated by any node that detects a bus error. An error frame consists of two fields: an error flag field and an error delimiter field.

- Overload Frame:

  An overload frame can be generated by a node as a result of two conditions. First, the node detects a dominant bit during interframe space which is an illegal condition. Second, due to internal conditions, the node is not yet able to start reception of the next message. A node may generate a maximum of 2 sequential overload frames to delay the start of the next message.

- Interframe Space:

  Interframe space separates a proceeding frame (of whatever type) from a following data or remote frame.

**REGISTER 19-31: CiTRBnSTAT: ECAN™ MODULE RECEIVE BUFFER n STATUS (n = 0, 1, ..., 31)**

| U-0 | U-0 | U-0 | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x |
|---|---|---|---|---|---|---|---|
| — | — | — | FILHIT4 | FILHIT3 | FILHIT2 | FILHIT1 | FILHIT0 |
| bit 15 | | | | | | | bit 8 |

| U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
|---|---|---|---|---|---|---|---|
| — | — | — | — | — | — | — | — |
| bit 7 | | | | | | | bit 0 |

| **Legend:** | | | |
|---|---|---|---|
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read as ‘0’ | |
| -n = Value at POR | ‘1’ = Bit is set | ‘0’ = Bit is cleared | x = Bit is unknown |

| | |
|---|---|
| bit 15-13 | **Unimplemented:** Read as ‘0’ |
| bit 12-8 | **FILHIT<4:0>:** Filter Hit Code bits (only written by module for receive buffers, unused for transmit buffers)<br>Encodes number of filter that resulted in writing this buffer. |
| bit 7-0 | **Unimplemented:** Read as ‘0’ |

# 20.0 10-BIT/12-BIT ANALOG-TO-DIGITAL CONVERTER (ADC)

> **Note:** This data sheet summarizes the features of the PIC24HJXXXGPX06/X08/X10 family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"PIC24H Family Reference Manual"*, **Section 16. "Analog-to-Digital Converter (ADC)"** (DS70225), which is available from the Microchip website (www.microchip.com).

The PIC24HJXXXGPX06/X08/X10 devices have up to 32 Analog-to-Digital input channels. These devices also have up to 2 Analog-to-Digital converter modules (ADCx, where 'x' = 1 or 2), each with its own set of Special Function Registers.

The AD12B bit (ADxCON1<10>) allows each of the ADC modules to be configured by the user as either a 10-bit, 4-sample/hold ADC (default configuration) or a 12-bit, 1-sample/hold ADC.

> **Note:** The ADC module needs to be disabled before modifying the AD12B bit.

## 20.1 Key Features

The 10-bit ADC configuration has the following key features:

- Successive Approximation (SAR) conversion
- Conversion speeds of up to 1.1 Msps
- Up to 32 analog input pins
- External voltage reference input pins
- Simultaneous sampling of up to four analog input pins
- Automatic Channel Scan mode
- Selectable conversion trigger source
- Selectable Buffer Fill modes
- Two result alignment options (signed/unsigned)
- Operation during CPU Sleep and Idle modes

The 12-bit ADC configuration supports all the above features, except:

- In the 12-bit configuration, conversion speeds of up to 500 ksps are supported
- There is only 1 sample/hold amplifier in the 12-bit configuration, so simultaneous sampling of multiple channels is not supported.

Depending on the particular device pinout, the Analog-to-Digital Converter can have up to 32 analog input pins, designated AN0 through AN31. In addition, there are two analog input pins for external voltage reference connections. These voltage reference inputs may be shared with other analog input pins. The actual number of analog input pins and external voltage reference input configuration will depend on the specific device. Refer to the device data sheet for further details.

A block diagram of the Analog-to-Digital Converter is shown in Figure 20-1.

## 20.2 Analog-to-Digital Initialization

The following configuration steps should be performed.

1. Configure the ADC module:
   a) Select port pins as analog inputs (ADxPCFGH<15:0> or ADxPCFGL<15:0>)
   b) Select voltage reference source to match expected range on analog inputs (ADxCON2<15:13>)
   c) Select the analog conversion clock to match desired data rate with processor clock (ADxCON3<7:0>)
   d) Determine how many S/H channels will be used (ADxCON2<9:8> and ADxPCFGH<15:0> or ADxPCFGL<15:0>)
   e) Select the appropriate sample/conversion sequence (ADxCON1<7:5> and ADxCON3<12:8>)
   f) Select how conversion results are presented in the buffer (ADxCON1<9:8>)
   g) Turn on the ADC module (ADxCON1<15>)
2. Configure ADC interrupt (if required):
   a) Clear the ADxIF bit
   b) Select ADC interrupt priority

## 20.3 ADC and DMA

If more than one conversion result needs to be buffered before triggering an interrupt, DMA data transfers can be used. Both ADC1 and ADC2 can trigger a DMA data transfer. If ADC1 or ADC2 is selected as the DMA IRQ source, a DMA transfer occurs when the AD1IF or AD2IF bit gets set as a result of an ADC1 or ADC2 sample conversion sequence.

The SMPI<3:0> bits (ADxCON2<5:2>) are used to select how often the DMA RAM buffer pointer is incremented.

The ADDMABM bit (ADxCON1<12>) determines how the conversion results are filled in the DMA RAM buffer area being used for ADC. If this bit is set, DMA buffers are written in the order of conversion. The module will provide an address to the DMA channel that is the same as the address used for the non-DMA stand-alone buffer. If the ADDMABM bit is cleared, then DMA buffers are written in Scatter/Gather mode. The module will provide a scatter/gather address to the DMA channel, based on the index of the analog input and the size of the DMA buffer.

## 21.0 SPECIAL FEATURES

> **Note:** This data sheet summarizes the features of the PIC24HJXXXGPX06/X08/X10 families of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 23. "CodeGuard™ Security"** (DS70239), **Section 24. "Programming and Diagnostics"** (DS70246), and **Section 25. "Device Configuration"** (DS70231) in the *"PIC24H Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

PIC24HJXXXGPX06/X08/X10 devices include several features intended to maximize application flexibility and reliability, and minimize cost through elimination of external components. These are:

- Flexible Configuration
- Watchdog Timer (WDT)
- Code Protection and CodeGuard™ Security
- JTAG Boundary Scan Interface
- In-Circuit Serial Programming™ (ICSP™) programming capability
- In-Circuit Emulation

### 21.1 Configuration Bits

The Configuration bits can be programmed (read as '0'), or left unprogrammed (read as '1'), to select various device configurations. These bits are mapped starting at program memory location 0xF80000.

The device Configuration register map is shown in Table 21-1.

The individual Configuration bit descriptions for the FBS, FSS, FGS, FOSCSEL, FOSC, FWDT and FPOR Configuration registers are shown in Table 21-2.

Note that address 0xF80000 is beyond the user program memory space. In fact, it belongs to the configuration memory space (0x800000-0xFFFFFF), which can only be accessed using table reads and table writes.

The upper byte of all device Configuration registers should always be '1111 1111'. This makes them appear to be `NOP` instructions in the remote event that their locations are ever executed by accident. Since Configuration bits are not implemented in the corresponding locations, writing '1's to these locations has no effect on device operation.

To prevent inadvertent configuration changes during code execution, all programmable Configuration bits are write-once. After a bit is initially programmed during a power cycle, it cannot be written to again. Changing a device configuration requires that power to the device be cycled.

**TABLE 21-1: DEVICE CONFIGURATION REGISTER MAP**

| Address | Name | Bit 7 | Bit 6 | Bit 5 | Bit 4 | Bit 3 | Bit 2 | Bit 1 | Bit 0 |
|---|---|---|---|---|---|---|---|---|---|
| 0xF80000 | FBS | RBS<1:0> | | — | — | BSS<2:0> | | | BWRP |
| 0xF80002 | FSS | RSS<1:0> | | — | — | SSS<2:0> | | | SWRP |
| 0xF80004 | FGS | — | — | — | — | — | GSS<1:0> | | GWRP |
| 0xF80006 | FOSCSEL | IESO | Reserved(2) | — | — | — | FNOSC<2:0> | | |
| 0xF80008 | FOSC | FCKSM<1:0> | | — | — | — | OSCIOFNC | POSCMD<1:0> | |
| 0xF8000A | FWDT | FWDTEN | WINDIS | — | WDTPRE | WDTPOST<3:0> | | | |
| 0xF8000C | FPOR | — | — | — | — | — | FPWRT<2:0> | | |
| 0xF8000E | FICD | Reserved(1) | | JTAGEN | — | — | — | ICS<1:0> | |
| 0xF80010 | FUID0 | User Unit ID Byte 0 | | | | | | | |
| 0xF80012 | FUID1 | User Unit ID Byte 1 | | | | | | | |
| 0xF80014 | FUID2 | User Unit ID Byte 2 | | | | | | | |
| 0xF80016 | FUID3 | User Unit ID Byte 3 | | | | | | | |

**Note 1:** When read, these bits will appear as '1'. When you write to these bits, set these bits to '1'.

**2:** When read, this bit returns the current programmed value.

## 24.1 DC Characteristics

**TABLE 24-1: OPERATING MIPS VS. VOLTAGE**

| Characteristic | $V_{DD}$ Range (in Volts) | Temp Range (in °C) | Max MIPS |
|---|---|---|---|
| | | | PIC24HJXXXGPX06/X08/X10 |
| | 3.0-3.6V | -40°C to +85°C | 40 |

**TABLE 24-2: THERMAL OPERATING CONDITIONS**

| Rating | Symbol | Min | Typ | Max | Unit |
|---|---|---|---|---|---|
| Industrial Temperature Devices | | | | | |
| Operating Junction Temperature Range | $T_J$ | -40 | — | +125 | °C |
| Operating Ambient Temperature Range | $T_A$ | -40 | — | +85 | °C |
| Power Dissipation:<br>Internal chip power dissipation:<br>$P_{INT} = V_{DD} \times (I_{DD} - \Sigma I_{OH})$<br>I/O Pin Power Dissipation:<br>$I/O = \Sigma (\{V_{DD} - V_{OH}\} \times I_{OH}) + \Sigma (V_{OL} \times I_{OL})$ | $P_D$ | $P_{INT} + P_{I/O}$ | | | W |
| Maximum Allowed Power Dissipation | $P_{DMAX}$ | $(T_J - T_A)/\theta_{JA}$ | | | W |

**TABLE 24-3: THERMAL PACKAGING CHARACTERISTICS**

| Characteristic | Symbol | Typ | Max | Unit | Notes |
|---|---|---|---|---|---|
| Package Thermal Resistance, 100-pin TQFP (14x14x1 mm) | $\theta_{JA}$ | 40 | — | °C/W | **1** |
| Package Thermal Resistance, 100-pin TQFP (12x12x1 mm) | $\theta_{JA}$ | 40 | — | °C/W | **1** |
| Package Thermal Resistance, 64-pin TQFP (10x10x1 mm) | $\theta_{JA}$ | 40 | — | °C/W | **1** |

**Note 1:** Junction to ambient thermal resistance, Theta-JA ($\theta_{JA}$) numbers are achieved by package simulations.

**FIGURE 24-2: EXTERNAL CLOCK TIMING**

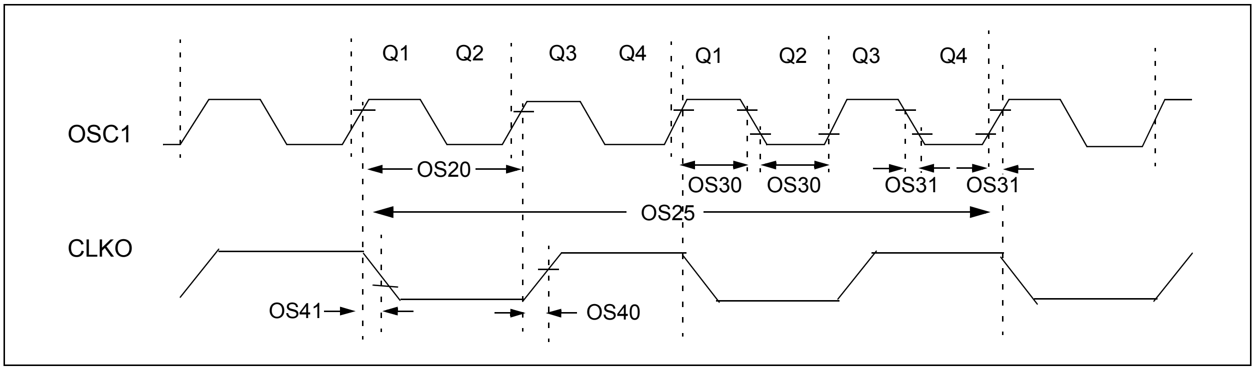



**TABLE 24-16: EXTERNAL CLOCK TIMING REQUIREMENTS**

| **AC CHARACTERISTICS** | | | **Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)**<br>Operating temperature -40°C ≤ TA ≤ +85°C for Industrial | | | | |
|---|---|---|---|---|---|---|---|
| **Param No.** | **Symbol** | **Characteristic** | **Min** | **Typ(1)** | **Max** | **Units** | **Conditions** |
| OS10 | FIN | External CLKI Frequency (External clocks allowed only in EC and ECPLL modes) | DC | — | 40 | MHz | EC |
| | | Oscillator Crystal Frequency | 3.5<br>10<br> | —<br>—<br>— | 10<br>40<br>33 | MHz<br>MHz<br>kHz | XT<br>HS<br>SOSC |
| OS20 | TOSC | TOSC = 1/FOSC | 12.5 | — | DC | ns | — |
| OS25 | TCY | Instruction Cycle Time(2) | 25 | — | DC | ns | — |
| OS30 | TosL, TosH | External Clock in (OSC1) High or Low Time | 0.375 x TOSC | — | 0.625 x TOSC | ns | EC |
| OS31 | TosR, TosF | External Clock in (OSC1) Rise or Fall Time | — | — | 20 | ns | EC |
| OS40 | TckR | CLKO Rise Time(3) | — | 5.2 | — | ns | — |
| OS41 | TckF | CLKO Fall Time(3) | — | 5.2 | — | ns | — |
| OS42 | GM | External Oscillator Transconductance(4) | 14 | 16 | 18 | mA/V | VDD = 3.3V<br>TA = +25ºC |

**Note 1:** Data in “Typ” column is at 3.3V, 25°C unless otherwise stated.

**2:** Instruction cycle period (TCY) equals two times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at “min.” values with an external clock applied to the OSC1/CLKI pin. When an external clock input is used, the “max.” cycle time limit is “DC” (no clock) for all devices.

**3:** Measurements are taken in EC mode. The CLKO signal is measured on the OSC2 pin.

**4:** Data for this parameter is Preliminary. This parameter is characterized, but not tested in manufacturing.

### TABLE 24-21: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER TIMING REQUIREMENTS

| AC CHARACTERISTICS | | | Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)<br>Operating temperature -40°C ≤ TA ≤ +85°C for Industrial | | | | |
|---|---|---|---|---|---|---|---|
| Param No. | Symbol | Characteristic(1) | Min | Typ(2) | Max | Units | Conditions |
| SY10 | TMCL | $\overline{\text{MCLR}}$ Pulse-Width (low) | 2 | — | — | μs | -40°C to +85°C |
| SY11 | TPWRT | Power-up Timer Period | — | 2<br>4<br>8<br>16<br>32<br>64<br>128 | — | ms | -40°C to +85°C<br>User programmable |
| SY12 | TPOR | Power-on Reset Delay | 3 | 10 | 30 | μs | -40°C to +85°C |
| SY13 | TIOZ | I/O High-Impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset | 0.68 | 0.72 | 1.2 | μs | — |
| SY20 | TWDT1 | Watchdog Timer Time-out Period | — | — | — | — | See **Section 21.4 "Watchdog Timer (WDT)"** and LPRC specification F21 (Table 24-19) |
| SY30 | TOST | Oscillator Start-up Timer Period | — | 1024 TOSC | — | — | TOSC = OSC1 period |
| SY35 | TFSCM | Fail-Safe Clock Monitor Delay | — | 500 | 900 | μs | -40°C to +85°C |

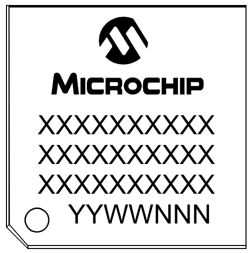
**Note 1:** These parameters are characterized but not tested in manufacturing.
**2:** Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

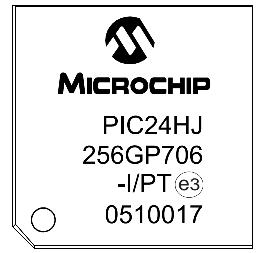
# 25.0 PACKAGING INFORMATION

## 25.1 Package Marking Information

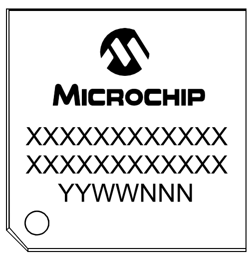
64-Lead TQFP (10x10x1 mm)



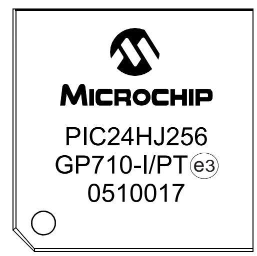

Example



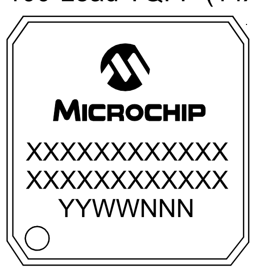

100-Lead TQFP (12x12x1 mm)



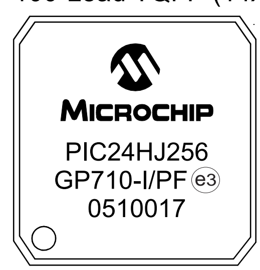

Example




100-Lead TQFP (14x14x1mm)




100-Lead TQFP (14x14x1mm)

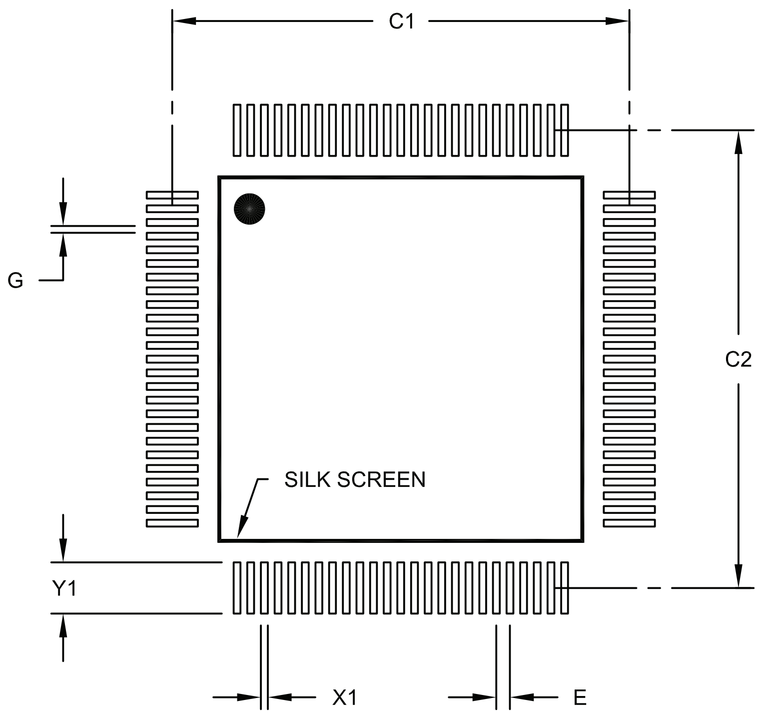



| | | |
|---|---|---|
| **Legend:** | XX...X | Customer-specific information |
| | Y | Year code (last digit of calendar year) |
| | YY | Year code (last 2 digits of calendar year) |
| | WW | Week code (week of January 1 is week '01') |
| | NNN | Alphanumeric traceability code |
| | (e3) | Pb-free JEDEC designator for Matte Tin (Sn) |
| | * | This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package. |

**Note:** In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

### 100-Lead Plastic Thin Quad Flatpack (PT) – 12x12x1 mm Body, 2.00 mm [TQFP]

| | |
|---|---|
| **Note:** | For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging |




RECOMMENDED LAND PATTERN

| Units | | MILLIMETERS | | |
|---|---|---|---|---|
| Dimension Limits | | MIN | NOM | MAX |
| Contact Pitch | E | 0.40 BSC | | |
| Contact Pad Spacing | C1 | | 13.40 | |
| Contact Pad Spacing | C2 | | 13.40 | |
| Contact Pad Width (X100) | X1 | | | 0.20 |
| Contact Pad Length (X100) | Y1 | | | 1.50 |
| Distance Between Pads | G | 0.20 | | |

Notes:

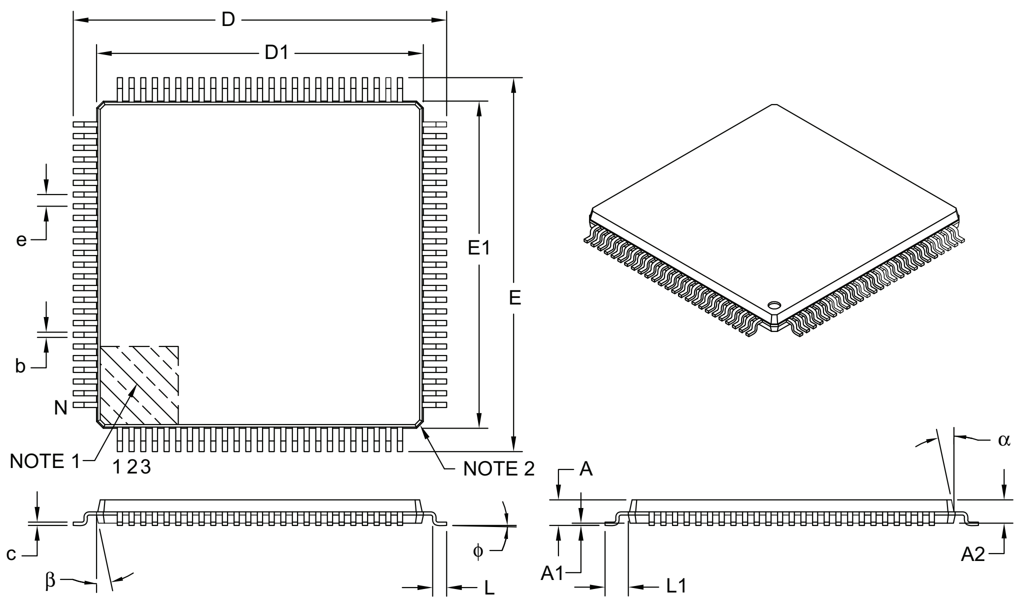
1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2100A

## 100-Lead Plastic Thin Quad Flatpack (PF) – 14x14x1 mm Body, 2.00 mm Footprint [TQFP]

| | |
|---|---|
| **Note:** | For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging |




| | Units | MILLIMETERS | | |
|---|---|---|---|---|
| | Dimension Limits | MIN | NOM | MAX |
| Number of Leads | N | 100 | | |
| Lead Pitch | e | 0.50 BSC | | |
| Overall Height | A | – | – | 1.20 |
| Molded Package Thickness | A2 | 0.95 | 1.00 | 1.05 |
| Standoff | A1 | 0.05 | – | 0.15 |
| Foot Length | L | 0.45 | 0.60 | 0.75 |
| Footprint | L1 | 1.00 REF | | |
| Foot Angle | φ | 0° | 3.5° | 7° |
| Overall Width | E | 16.00 BSC | | |
| Overall Length | D | 16.00 BSC | | |
| Molded Package Width | E1 | 14.00 BSC | | |
| Molded Package Length | D1 | 14.00 BSC | | |
| Lead Thickness | c | 0.09 | – | 0.20 |
| Lead Width | b | 0.17 | 0.22 | 0.27 |
| Mold Draft Angle Top | α | 11° | 12° | 13° |
| Mold Draft Angle Bottom | β | 11° | 12° | 13° |

**Notes:**

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-110B

### Revision H (March 2009)

This revision includes minor typographical and formatting changes throughout the data sheet text.

Global changes include:

- Changed all instances of OSCI to OSC1 and OSCO to OSC2
- Changed all instances of VDDCORE and VDDCORE/VCAP to VCAP/VDDCORE

The other changes are referenced by their respective section in the following table.

**TABLE A-2: MAJOR SECTION UPDATES**

| Section Name | Update Description |
|---|---|
| **"High-Performance, 16-Bit Microcontrollers"** | Updated all pin diagrams to denote the pin voltage tolerance (see **"Pin Diagrams"**).<br><br>Added Note 2 to the 28-Pin QFN-S and 44-Pin QFN pin diagrams, which references pin connections to VSS. |
| **Section 1.0 "Device Overview"** | Updated AVDD in the PINOUT I/O Descriptions (see Table 1-1). |
| **Section 2.0 "Guidelines for Getting Started with 16-Bit Microcontrollers"** | Added new section to the data sheet that provides guidelines on getting started with 16-bit Microcontrollers. |
| **Section 4.0 "Memory Organization"** | Add Accumulator A and B SFRs (ACCAL, ACCAH, ACCAU, ACCBL, ACCBH and ACCBU) and updated the Reset value for CORCON in the CPU Core Register Map (see Table 4-1).<br><br>Updated Reset values for IPC3, IPC4, IPC11 and IPC13-IPC15 in the Interrupt Controller Register Map (see Table 4-5).<br><br>Updated the Reset value for CLKDIV in the System Control Register Map (see Table 4-31). |
| **Section 5.0 "Flash Program Memory"** | Updated **Section 5.3 "Programming Operations"** with programming time formula. |
| **Section 9.0 "Oscillator Configuration"** | Added Note 2 to the Oscillator System Diagram (see Figure 9-1).<br><br>Updated default bit values for DOZE<2:0> and FRCDIV<2:0> in the Clock Divisor (CLKDIV) Register (see Register 9-2).<br><br>Added a paragraph regarding FRC accuracy at the end of **Section 9.1.1 "System Clock sources"**.<br><br>Added Note 1 to the FRC Oscillator Tuning (OSCTUN) Register (see Register 9-4). |
| **Section 10.0 "Power-Saving Features"** | Added the following registers:<br><br>• PMD1: Peripheral Module Disable Control Register 1 (Register 10-1)<br>• PMD2: Peripheral Module Disable Control Register 2 (Register 10-2)<br>• PMD3: Peripheral Module Disable Control Register 3 (Register 10-3) |
| **Section 11.0 "I/O Ports"** | Added reference to pin diagrams for I/O pin availability and functionality (see **Section 11.2 "Open-Drain Configuration"**). |
| **Section 16.0 "Serial Peripheral Interface (SPI)"** | Added Note 2 to the SPIxCON1 register (see Register 16-2). |
| **Section 18.0 "Universal Asynchronous Receiver Transmitter (UART)"** | Updated the UTXINV bit settings in the UxSTA register (see Register 18-2). |